

MAY.28.2002 8:25AM RWS GROUP, LLC

Abstract

A disk-shaped wafer is described which is based on an inorganic sorbent and a binder, with a thickness of less than 700 microns, which can be obtained by pressing a mixture of the inorganic sorbent, roughly 20 to 60% by weight of the binder and roughly 10 to 15% by weight water at a pressure of at least 70 MPa; and calcination of the resulting green wafer at temperatures of at least roughly 500°C until the water content is largely removed.

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